



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



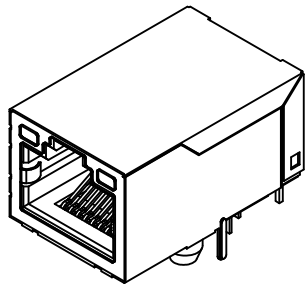
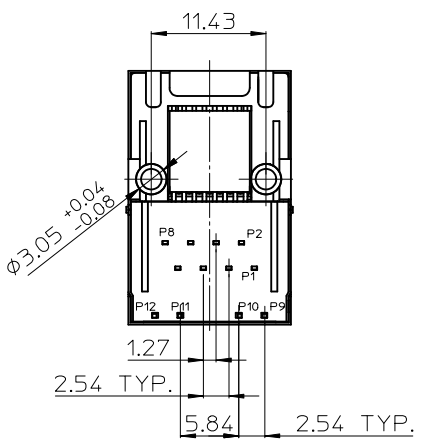
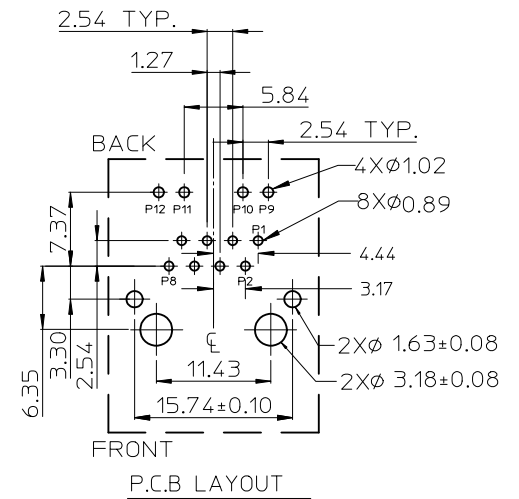
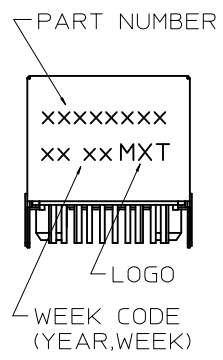
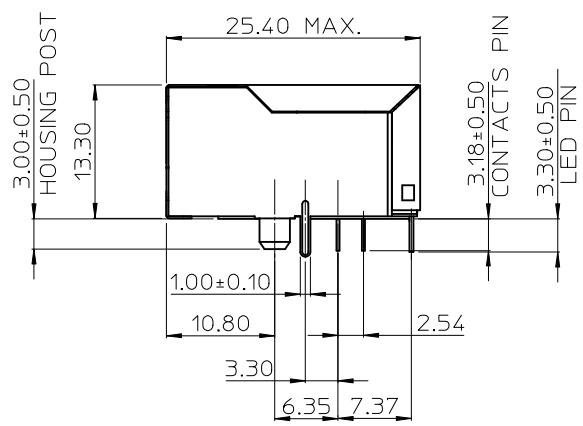
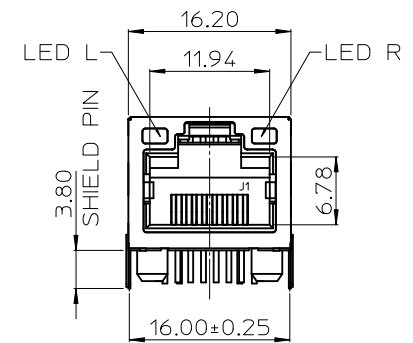
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NOTES:

- MATERIAL:  
METAL SHELL: BRASS  
HOUSING: POLYAMIDE, GLASS FIBER FILLED, UL94-0,COLOR BLACK  
INSERT: POLYAMIDE, GLASS FIBER FILLED, UL94-0,COLOR BLACK  
TERMINAL: PHOSPHOR BRONZE
- PLATING:  
TERMINAL:  
CONTACT AREA: GOLD(Au),THICKNESS=50 MICROINCH/1.27 MICROMETER  
SOLDER TAIL: TIN(Sn),THICKNESS=100 MICROINCH MINIMUM  
UNDER PLATE: NICKEL (Ni).
- METAL SHELL:  
SOLDER TAIL: TIN(Sn),THICKNESS=100 MICROINCH MINIMUM  
UNDER PLATE: NICKEL (Ni),(SOLDERING AVAILABLE)  
SURFACE APPEARANCE: BRIGHT.
- RECOMMENDED PCB THICKNESS: 1.60±0.05
- PRODUCT SPECIFICATION REFER TO PS-48025-005
- TEST SUMMARY REFER TO TS-48025-012
- PACKAGING SPECIFICATION REFER TO PK-48025-001
- LEAD FREE AND RoHS COMPLIANT PRODUCT.

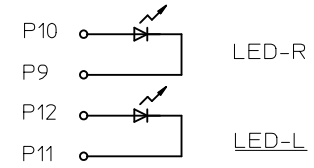
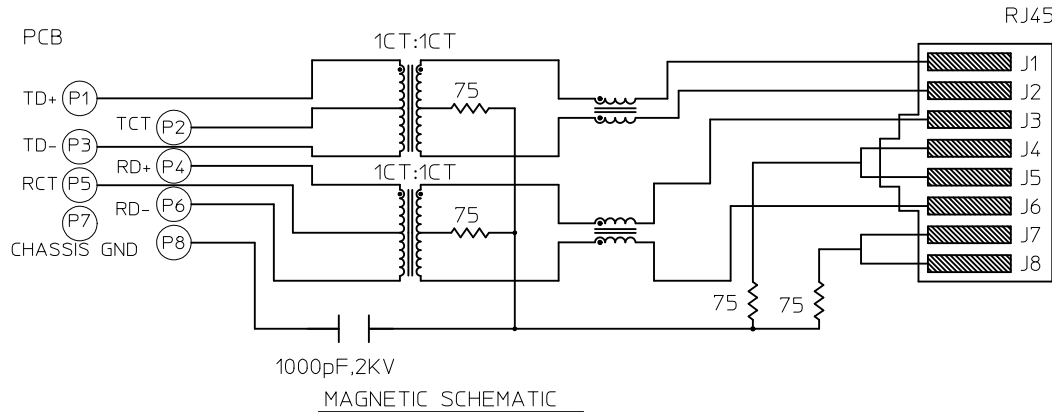
RELEASED EC NO: SH2012-0381 DRWN:RL 109 CHKD: APPR:RZHANG 2012/05/14 2012/06/22	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY LINDA LIN	DATE 2006/11/16	TITLE MODULAR JACK WITH INTEGRATED MAGNETICS WITH LED W/O EMI FINGER				
		3 PLACES ± --- ± ---		CHECKED BY ALLEN LIN	DATE 2006/11/17	molex				
		2 PLACES ± 0.25 ± ---		APPROVED BY ERICK LAN	DATE 2006/11/17					
1 PLACE ± 0.25 ± ---		MATERIAL NO. 48025-1091		DOCUMENT NO. SD-48025-012		SHEET NO. 1 OF 2				
0 PLACE ± ±		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

MAGNETIC ELECTRICAL SPECIFICATIONS:

- 1.0 TURNS RATIO:(P4-P5-P6):(J3-J6):1CT:1CT  
(P3-P2-P1):(J1-J2):1CT:1CT
- 2.0 INDUCTANCE:(P4-P6):350uH MIN. @0.1V,100KHz,8mA DC Bias.  
(P3-P1):350uH MIN. @0.1V,100KHz,8mA DC Bias.
- 3.0 LEAKAGE INDUCTANCE:P6-P5-P4(WITH J6 AND J3 SHORT):0.3 MAX.@1MHz.  
P3-P2-P1(WITH J2 AND J1 SHORT):0.3 MAX.@1MHz.
- 4.0 INTERWINDING CAPACITANCE:(P6,P5,P4) TO (J6,J3):30pf MAX @1MHz.  
(P3,P2,P1) TO (J2,J1):30pf MAX @1MHz.
- 5.0 DC RESISTANCE:(J6-J3)=(J2-J1):1.3 ohms Max.
- 6.0 RETURN LOSS:(P4-P6)(P1-P3)  
1MHz TO 30MHz:18dB min.  
30MHz TO 80MHz:12dB min.  
NOTE:100 OHMS CONNECTED TO (J2-J1) OR (J3-J6).
- 7.0 HI-POT:(J1,J2) TO (P1,P3):1500 VAC OR 2250 VDC.  
(J3,J6) TO (P4,P6):1500 VAC OR 2250 VDC.
- 8.0 INSERTION LOSS:1.1 dB MAX.  
100KHz TO 100MHz.
- 9.0 CROSS TALK:1-100 MHz:30 dB MIN.
- 10.0 COMMON TO COMMON MODE REJECTION:1MHz TO 100MHz:35 dB MIN.

LED ELECTRICAL SPECIFICATION

PARAMETER	GREEN (TYP.)	UNITS	TEST CONDITIONS
POWER DISSIPATION	105	mW	
REVERSE VOLTAGE	5	V	
PEAK WAVELENGTH	565	nm	IF=20mA
FORWARD VOLTAGE	2.2 MAX.=2.5	V	IF=20mA



RELEASED EC NO: SH2012-0381 DRW:RL109 2012/05/14 CHKD: APPR:RZHANG 2012/06/22	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		▼=0 ▽=0	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ±        ±	MM ONLY	1:1	METRIC	
		ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: LINDA LIN CHECKED BY: ALLEN LIN APPROVED BY: ERICK LAN DATE: 2006/11/16 DATE: 2006/11/17 DATE: 2006/11/17	TITLE	MODULAR JACK WITH INTEGRATED MAGNETICS WITH LED W/O EMI FINGER <b>molex</b>		
		MATERIAL NO. 48025-1091 DOCUMENT NO. SD-48025-012 SHEET NO. 2 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				